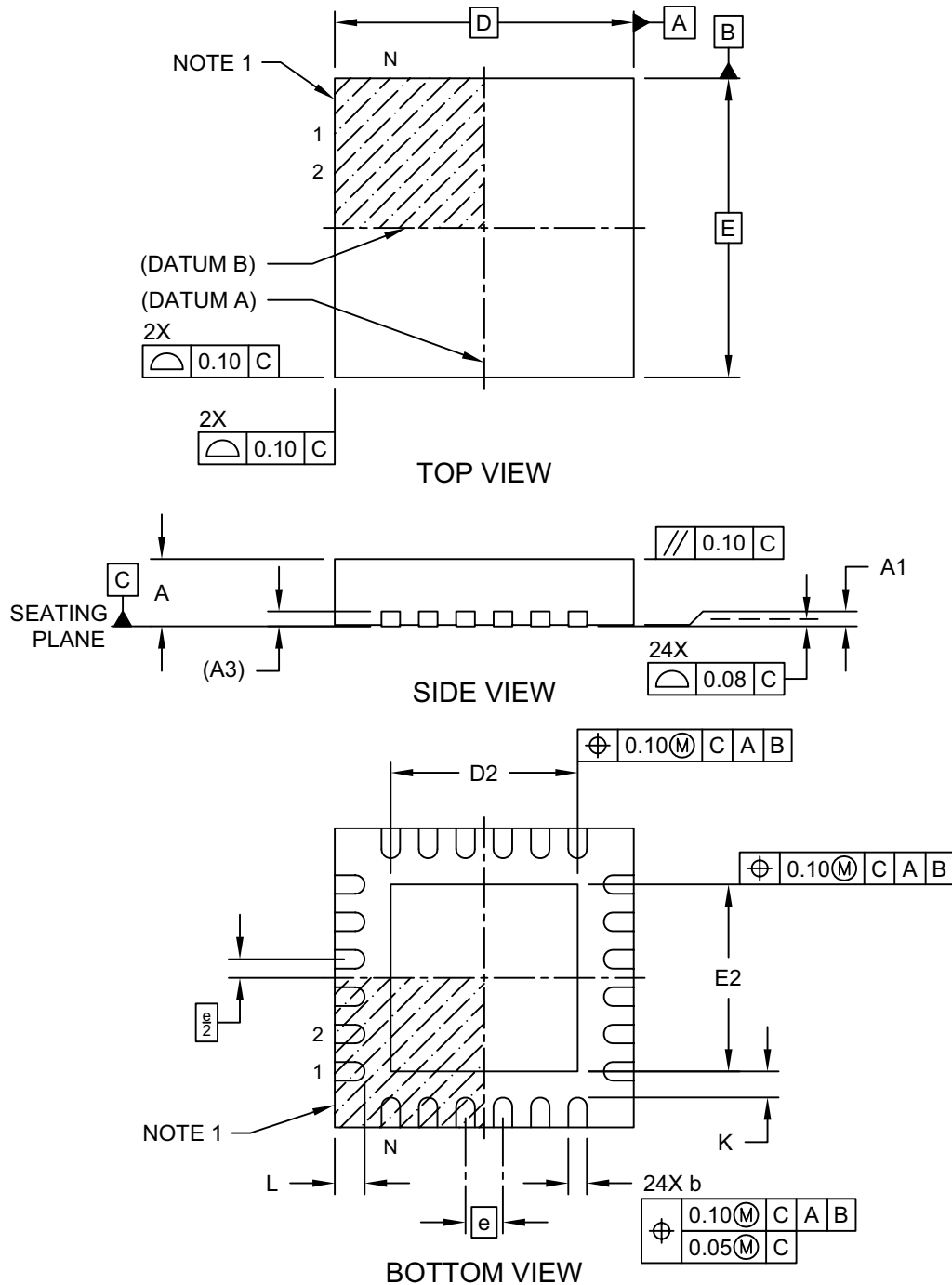


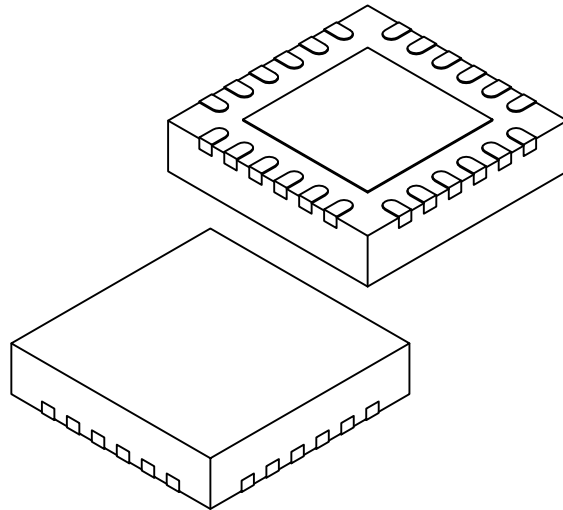
**24-Lead Very Thin Plastic Quad Flat, No Lead Package (MJ) – 4x4x0.9 mm Body [VQFN]
SMSC Legacy S4QFN**

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



**24-Lead Very Thin Plastic Quad Flat, No Lead Package (MJ) – 4x4x0.9 mm Body [VQFN]
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Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Number of Terminals	N	24		
Pitch	e	0.50 BSC		
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Terminal Thickness	A3	0.20 REF		
Overall Width	E	4.00 BSC		
Exposed Pad Width	E2	2.40	2.50	2.60
Overall Length	D	4.00 BSC		
Exposed Pad Length	D2	2.40	2.50	2.60
Terminal Width	b	0.18	0.25	0.30
Terminal Length	L	0.35	0.40	0.45
Terminal-to-Exposed Pad	K	0.25	-	-

Notes:

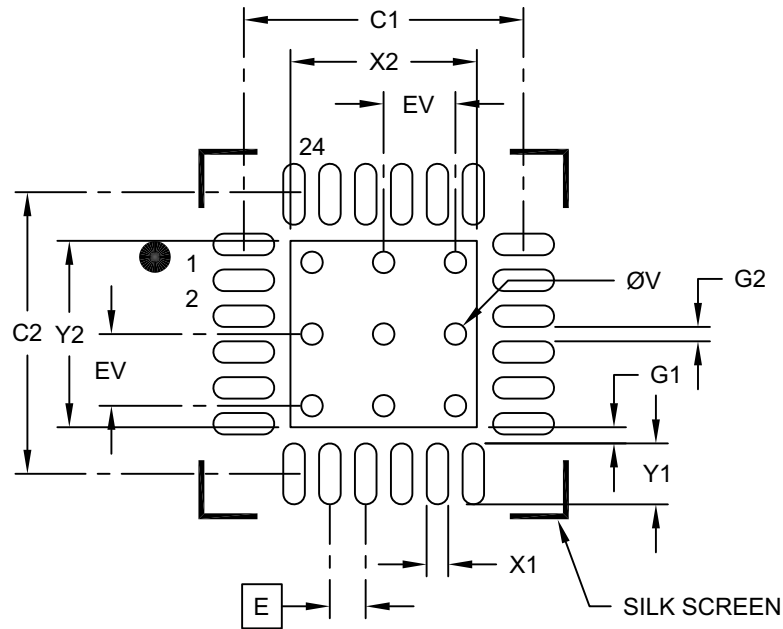
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated
3. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

**24-Lead Very Thin Plastic Quad Flat, No Lead Package (MJ) – 4x4x0.9 mm Body [VQFN]
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RECOMMENDED LAND PATTERN

Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Contact Pitch	E	0.50 BSC		
Optional Center Pad Width	X2			2.60
Optional Center Pad Length	Y2			2.60
Contact Pad Spacing	C1		3.90	
Contact Pad Spacing	C2		3.90	
Contact Pad Width (X24)	X1			0.30
Contact Pad Length (X24)	Y1			0.85
Contact Pad to Center Pad (X24)	G1	0.23		
Contact Pad to Contact Pad (X20)	G2	0.20		
Thermal Via Diameter	V		0.30	
Thermal Via Pitch	EV		1.00	

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
2. For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process

Microchip Technology Drawing C04-2143A S4QFN